Surface Modification using Atmospheric Plasma

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Abstract

Use of atmospheric pressure partial discharges (plasma and chemical corona) is becoming ubiquitous within the metallizing, laminating and converting industry. Plasma technology advances including control of gas mixture, temperature controlled high surface area electrodes, higher frequency power supplies and better matching networks all combine to make atmospheric plasma treatment a commercially important process wherever surface functionality is a factor. This process is now used to replace the use of corona and flame treatment in promoting adhesion to flexible packaging polyolefin materials such as polypropylene, polyester and polyethylene film webs at commercial speeds. Beyond surface treatment, atmospheric plasma systems can now be used to perform a Plasma Enhanced Chemical Vapor Deposition (PECVD) process that results in clear oxide layers such as SiO_x on plastic substrates. Emerging applications include ablation or cleaning to remove unwanted residue or material, elevation of surface energy to promote adhesion of ink, lamination adhesion or wetability, sterilization, and deposition of thin functional coatings. This paper will address surface modification applications based on the use of atmospheric plasma to clean, treat, graft and coat different substrates that include, polymer films, metallized films, ITO coated films, window glass, aluminum foil and woven and non woven fabrics.



Surface Functionalization of Materials

Common surface treatment processes

- · Mechanical: roughing of surface
- · Chemical: mostly wet chemical
- Partial Discharge: activated gases
 - Corona
 - Flame
 - Plasma (ionized or neutral)

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ATMOSPHERIC PRESSURE

Surface Functionalization of Material

- Surface Treatment in Atmosphere
 - Corona Limitations
 - Intense Filament Discharge Creation of LMW
 - Backside Treatment
 - Non Uniform
 - Flame Limitations
 - Fixed Chemistry
 - Can Damage Low Gage OPP
 - Speed Limitations
 - · Reduction in Film Clarity
 - · Requires Constant Monitoring of Treatment Levels

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PLASMA TREATER ELECTRODES

Surface Functionalization of Materials

- Available in Water-Cooled Ceramic and Aluminum
- Al Electrodes are used for Non-conductives
- Ceramic Electrodes are Used for : Treating Metallized Films and Foils
 - Treating on a Bare Metal Roll Treating Thick Sheets

Plasma Gas is Supplied Through the Electrodes

- Specialty Electrodes That can Treat Film Surfaces with No Roller No Underlying Ground Plane or Provide Neutral Plasma
- Treater rolls may be Bare Metal or Covered with Silicone Rubber, Polyurethene or Ceramic

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ATMOSPHERIC PLASMA ELECTRONICS PARTS TREATMENT Surface Functionalization of Mate

VS



•97% "Superior" Parts using **High O2 Atmospheric Plasma Treatment &** Leading Edge WC Electrodes

•80% "Good" Parts using Low O2, Old Generation **Electrodes and Pwr Supply** Technology

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WATER COOLED ALUMINUM **ELECTRODE SYSTEM** Surface Functionalization of Materials

Ideal for for BOPP, CPP, and PE Films

- Reduces LMW **Blooming to the Film** surface
- Mitigates thermal load **Maintains High Plasma**
- Volume in Gap
- Long Electrode Life
- Extends Treater Roll Life
- Inexpensive Aluminum Extrusion Construction



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ATMOSPHERIC PLASMA CONTROLLED ATMOSPHERE TREATER Surface Functionalization of Materials



 Innovative Electrode Design Precise Control of Plasma Gas Envelope Large Volume Plasma Rxn

Region

 Improved Plasma Gas Containment

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- Powders

- Polymer and Glass Sheets



· Atmospheric Plasma Reactors Can be used to: - Treat - Graft - Coat

Plasma Based Surface Functionalization is an Effective Tool to Add Value to Various Large Scale Surfaces that include: – Elexible Webs: Films, Fabrics, Foils, Paper, Non-wovens, etc

- Atmospheric Plasma Etching, Ashing, and CVD Based Deposition Processes will Grow Rapidly in the Near Future at the Expense of Vacuum Plasma, Corona, Flame and Liquid Chemical Treatment and Deposition Processes

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